

Title (en)

HEAT PUMP SYSTEM AND CONTROL METHOD THEREFOR

Title (de)

HEIZPUMPENSYSTEM UND STEUERUNGSVERFAHREN DAFÜR

Title (fr)

SYSTÈME DE POMPE À CHALEUR ET PROCÉDÉ DE COMMANDE POUR CELUI-CI

Publication

**EP 3623726 A4 20200909 (EN)**

Application

**EP 19812899 A 20190603**

Priority

- CN 201820955994 U 20180620
- CN 201810638493 A 20180620
- CN 2019089850 W 20190603

Abstract (en)

[origin: EP3623726A1] A heat pump system (1) and a control method therefor are provided. The heat pump system (1) includes an outdoor heat exchanger (10) and an electromagnetic heating assembly (20). The electromagnetic heating assembly (20) includes an induction heating sheet (200), an insulation plate (210), and an electromagnetic induction wire coil (220). The induction heating sheet (200) is in contact with the outdoor heat exchanger (10), the electromagnetic induction wire coil (220) is attached to the insulation plate (210), the insulation plate (210) is connected to the outdoor heat exchanger (10) or the induction heating sheet (200), the induction heating sheet (200) is coupled with the electromagnetic induction wire coil (220) by communication.

IPC 8 full level

**F25B 30/02** (2006.01); **F25B 39/00** (2006.01); **F25B 39/02** (2006.01); **F25B 47/00** (2006.01)

CPC (source: EP)

**F25B 30/02** (2013.01); **F25B 39/00** (2013.01); **F25B 39/02** (2013.01); **F25B 39/022** (2013.01); **F25B 47/00** (2013.01); **F25B 2313/021** (2013.01)

Citation (search report)

- [XAY] EP 2159494 A2 20100303 - LG ELECTRONICS INC [KR]
- [XAY] WO 2014117511 A1 20140807 - HAIER GROUP CORP [CN], et al
- [XAY] KR 20090099612 A 20090923 - LG ELECTRONICS INC [KR]
- [XAY] EP 2410265 A1 20120125 - DAIKIN IND LTD [JP]
- [Y] US 2011314852 A1 20111229 - KINOSHITA HIDEHIKO [JP], et al
- See also references of WO 2019242493A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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